

Notification# 20180221003A
Datasheet for OPA211, OPA2211
Information Only

Correction: Datasheet revision history corrected for rev I to J and added corrections from rev J to K.

Date: October 31, 2018

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services


Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA211AIDR	null
OPA2211AIDDA	null
OPA211AID	null
OPA211AIDGKT	null
OPA211ID	null
OPA2211AIDRGT	null
OPA211IDR	null
OPA2211AIDDAR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180221003A	PCN Date:	October 31, 2018
Title:	Datasheet for OPA211, OPA2211		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	
Notification Details			
Description of Change:			
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p> <p>Correction: Datasheet revision history corrected for rev I to J and added corrections from rev J to K.</p>			
		OPA211, OPA2211 <small>SBOS377K – OCTOBER 2006 – REVISED SEPTEMBER 2018</small>	
Changes from Revision J (February 2018) to Revision K			Page
• Changed format of GPN from "OPA2x11" to "OPAx211"			1
• Corrected system-generated errors: "Time" units from "ms/div" back to "µs/div" and unit for resistors from "W" back to "Ω" in <i>Typical Characteristics</i>			14
• Corrected system-generated error in unit for resistors from "W" back to "Ω" in <i>Figure 43</i>			23
• Reverted <i>Figure 51</i> back to that of rev. I			31
Changes from Revision I (June 2016) to Revision J			Page
• Added "Medical Instrumentation" to <i>Applications</i> section.....			1
• Changed product status from mixed product status to production data			1
• Deleted <i>Device Comparison</i> table			4
• Added NC pin table notes to pin diagrams in the <i>Pin Configurations and Functions</i> section			4
• Changed formatting of document reference in <i>EMI Rejection</i> section			26
• Changed formatting of document references in <i>SON Layout Guidelines</i> section			31
• Changed formatting of document references in <i>Related Documentation</i> section			32
The datasheet number will be changing.			
Device Family	Change From:	Change To:	
OPA211, OPA2211	SBOS377I	SBOS377K	
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/OPA211			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			

Product Affected:			
OPA211AID	OPA211AIDR	OPA211ID	OPA211IDRGT
OPA211AIDG4	OPA211AIDRG4	OPA211IDGKR	OPA2211AIDDA
OPA211AIDGKR	OPA211AIDRGR	OPA211IDGKT	OPA2211AIDDAR
OPA211AIDGKT	OPA211AIDRGT	OPA211IDR	OPA2211AIDRGR
OPA211AIDGKTG4	OPA211AIDRGTG4	OPA211IDRGR	OPA2211AIDRGT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com